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V. B. M. J.  
3/4/03  
2811  
PATENT  
Customer No. 22,852  
Attorney Docket No. 04329.2686

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

**YOSHIKI SUGIZAKI**

) Group Art Unit: 2811

Serial No: 09/972,855

) Examiner: Junghwa M. Im

Filed: October 10, 2001

For: SEMICONDUCTOR DEVICE

Commissioner for Patents  
Washington, DC 20231

Sir:

**AMENDMENT**

In reply to the Office Action dated November 21, 2002, the non-fee period for response extending to February 21, 2003, please amend the application as follows.

**IN THE SPECIFICATION:**

Please amend the specification as follows:

Please replace the paragraph beginning on page 12, line 3 and continuing to page 13, line 4, with the following amended paragraph:

In FIG. 1A, a semiconductor chip 1 is mounted on a wiring substrate 7 through a conductive bump 4 so that a formation surface 2 of the semiconductor chip 1 on which a semiconductor element (internal circuit) is formed faces to a surface of the chip 1 side of the wiring substrate 7, which surface is on the side of the semiconductor chip 1, namely

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